

# MATERIAL DECLARATION SHEET



Material #	<b>2QSP20 Series</b>	
Product Line	Integrated Passive & Active Devices	
Date	2004/5/27	
Rev., date	A	

## COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Lead Frame	Lead Frame	0.0744	Cu	7440-50-8	95.53%	100	
				Ni	7440-02-0	0%		
				Sn	7440-31-5	4.46%		
2	Wafer	Silicon	0.01434	Silicon		98~99%	100	
				Other material		1~2%		
3	Gold Bond wire	Conductor	0.000352	Au	7440-57-5	99%	100	
				SI		1%		
4	Silver paste	Die Attach	0.000808	Ag		78~82%	100	
				Epoxy		18~22%		
5	Molding Component	Outer	0.0401	Silica fused	60676-86-0	75-95%	100	
				Epoxy resin		6-10%		
				Phenol resin		2-6%		
Total weight			0.1300					

Lead Part Number Example: 2QSP20-RJ2-103  
 Pb Free Part Number Example: 2QSP20-RJ2-103LF